ACCCULATION DOTTO	DEC 1 6 2005
Atty Docket No.: 265571US6PCT FORM PTO-1595 06-04 12-22-2	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Director of the United State	THAT I WAS A STATE OF THE STATE
 Name of conveying party(ies): 103142 Makoto URUSHIHARA Keisuke HIROI Hideyuki AGATA Takashi OHKUBO Additional name(s) of conveying party(ies) attached? ☐ Yes 	Name: SONY CORPORATION Address: 7-35 Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141, Japan
3. Nature of Conveyance: Assignment	er 16, Additional name(s) and address(es) attached? □ Yes ■ No
4. Application number(s) or patent number(s):	ation
☐ This document is being filed together with a new application A. Patent Application No.(s) 10/525,965	B. Patent No.(s)
Additional number	s attached? 🗆 Yes 🔳 No
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total applications and patents involved: 1
Customer Number 22850 Tel. (703) 413-3000 Fax. (703) 413-2220	7. Total fee (37 CFR 3.41): \$40.00 ■ Enclosed □ Authorized to be charged to deposit account 8. Deposit account number: 15-0030 (Attach duplicate copy of this page if paying by deposit account)
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Alexandria, Virginia. 22313

PATENT REEL: 017374 FRAME: 0501

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

NFORMATION PROCESSING APPARATUS AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in

the spaces that follow: International Filing Number: _____PCT/JP03/11190__, International Filing Date: ___September 2, 2003_.

This assignment executed on the dates indicated below. Makoto URUSHIHARA Name of first or sole inventor Execution date of U.S. Patent Application Tokyo, Japan Residence of First or sole inventor November 14, 2005

Date of this assignment Signature of first or sole inventor Keisuke HIROI Execution date of U.S. Patent Application Name of second inventor Tokyo, Japan Residence of second inventor November 16, 2005 Date of this assignment Keisuke Hiroi Signature of second inventor Hideyuki AGATA Execution date of U.S. Patent Application Name of third inventor Tokyo, Japan Residence of third inventor

Fiday Signature of third inventor November 11, 2005 Date of this assignment

(S)

ADDITIONAL INVENTOR(S)

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PATENT REEL: 017374 FRAME: 0502

Takashi OHKUBO	· · · · · · · · · · · · · · · · · · ·
Name of fourth inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of fourth inventor (akashi (haba)	November . (1, 2005) Date of this assignment
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment
Name of sixth inventor	Execution date of U.S. Patent Application
Residence of sixth inventor	
Signature of sixth inventor	Date of this assignment